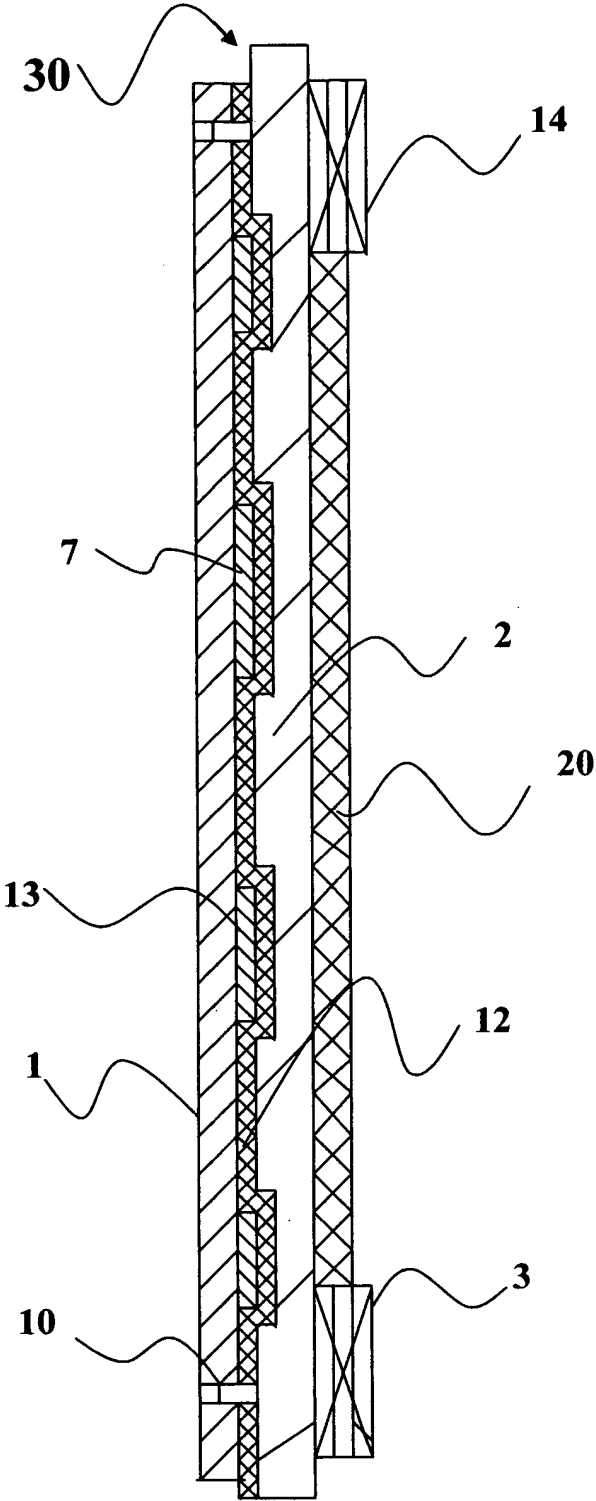


**FIG. 5**



**FIG. 6**

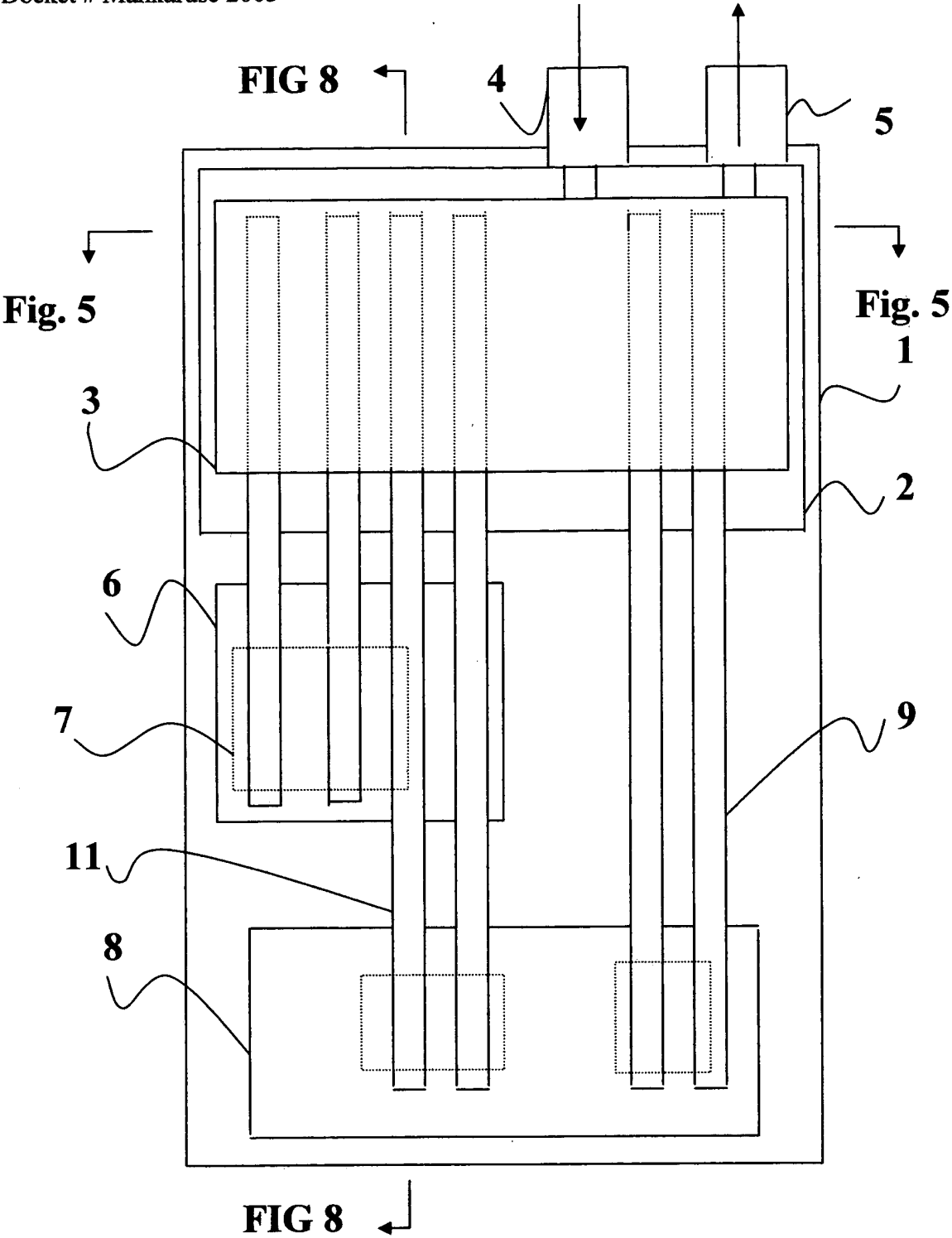
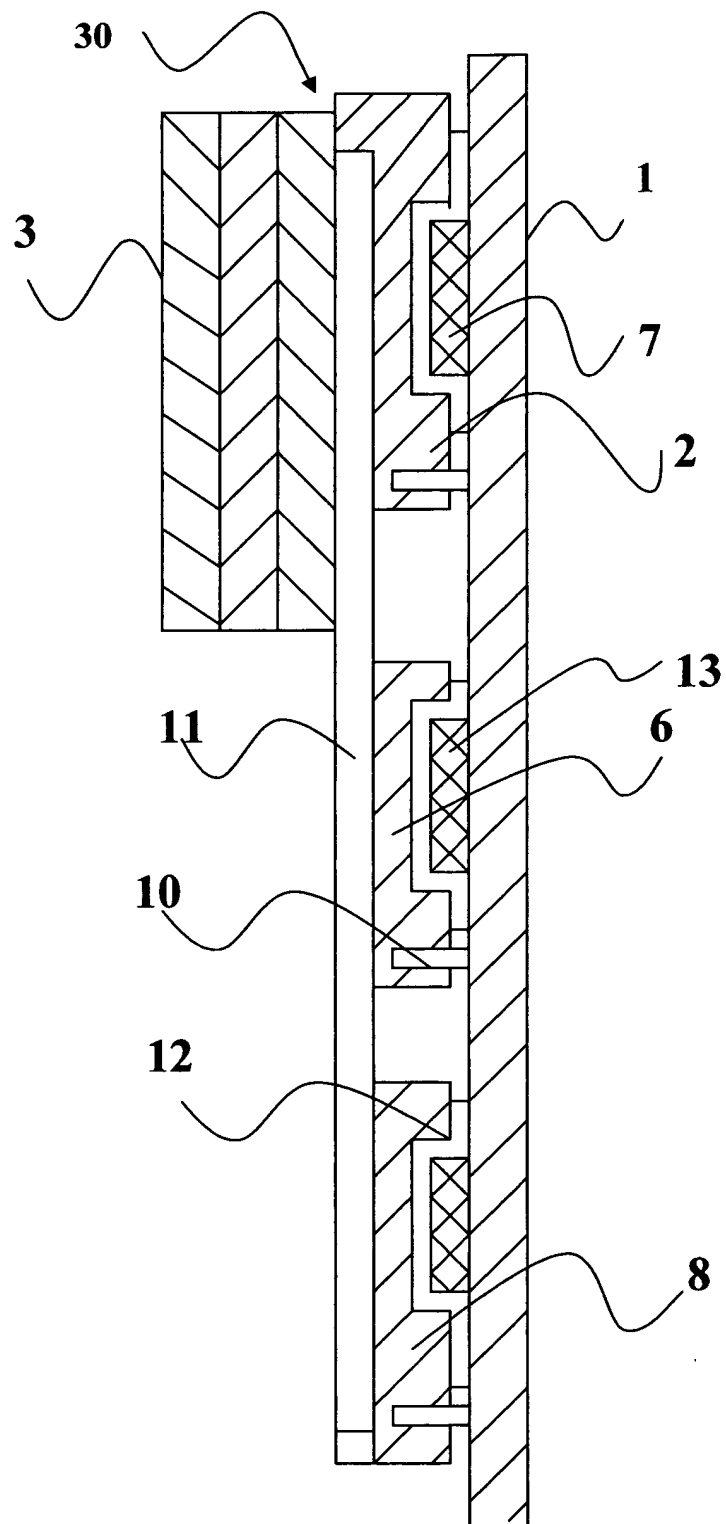
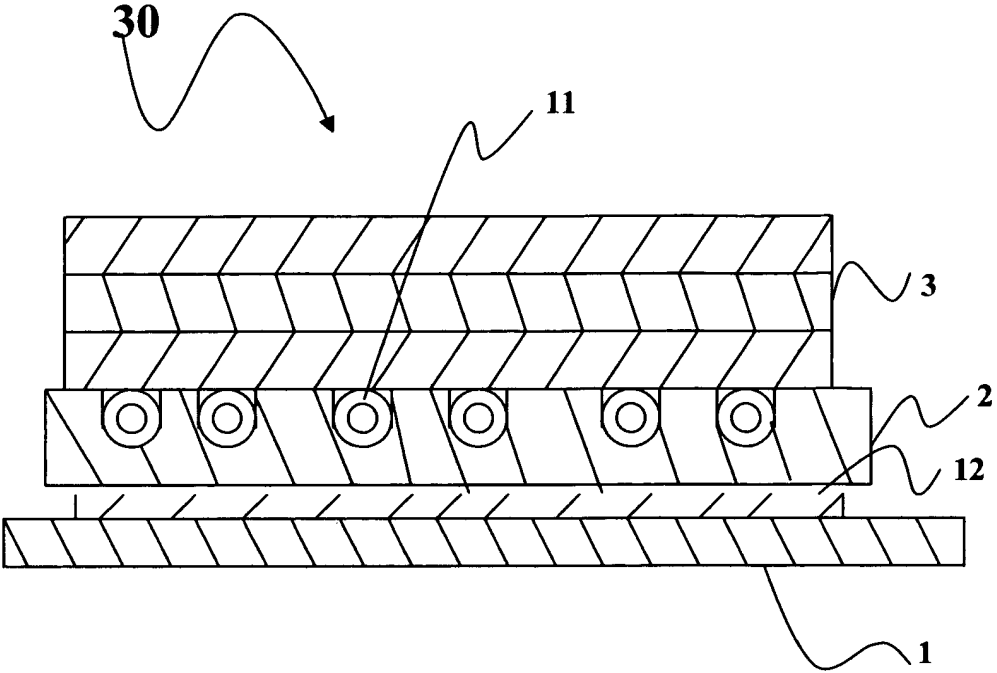


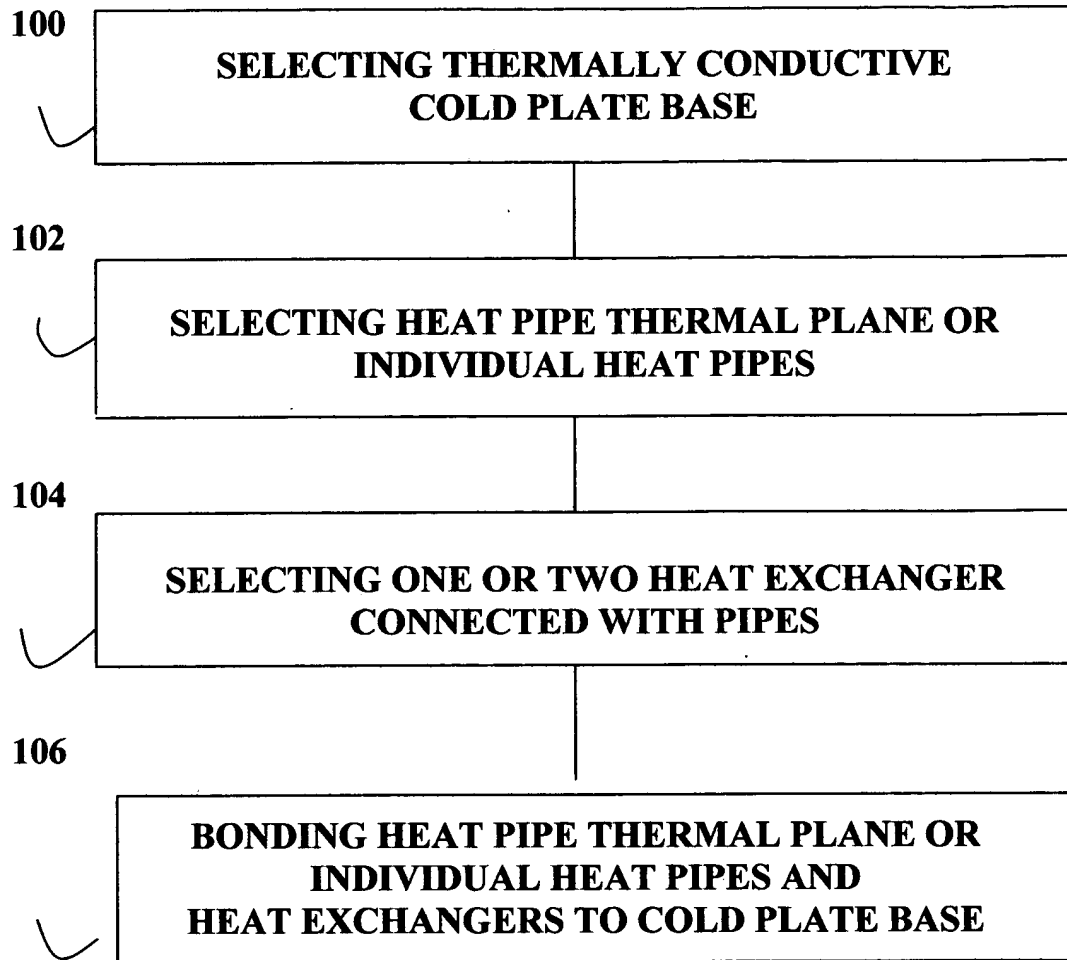
FIG. 7



**Fig. 8**



**Fig. 9**



**FIG. 10**



Docket # Mankaruse 2003

Reference Designation:

1	Electronic Circuit Board
2	Thermally Conductive Base
3	Fluid (liquid) Compact Heat Exchanger
4	Fluid (liquid) Quick Disconnect
5	Fluid (liquid) Quick Disconnect
6	Thermally conductive Base
7	Heat Dissipating Electronic Component
8	Thermally Conductive Base
9	Individual Heat Pipe
10	Align Pin
11	Individual Heat Pipe
12	Gap Filler (thermally conductive, electrically non-conductive)
13	Heat Dissipating Electronic Component
14	Fluid (liquid) Compact Heat Exchanger
15	Fluid Liquid Connection Pipe
16	Fluid Liquid Connection Pipe
20	Heat Pipe Thermal Plane
25	Cold Plate Assembly
30	Circuit Board and Cold Plate Assembly

Fig. 5 Front View of Circuit Board and Cold Plate Assembly

Fig. 6 Cross Sectional View As Indicated By arrows on Fig. 5

Fig. 7 Front View of Circuit Board and Cold plate Assembly

Fig. 8 Cross Sectional View As Indicated By Arrows on Fig. 7

Fig. 9 Cross Sectional View As Indicated By Arrows on Fig. 7

Fig. 10 Process of Cold Plate Production and Assembling